Hongbo Qin

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/8821251/publications.pdf

Version: 2024-02-01

22	384	1162889 8	839398 18
papers	citations	h-index	g-index

22	22	22	454
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	The Mechanical Properties and Elastic Anisotropies of Cubic Ni3Al from First Principles Calculations. Crystals, 2018, 8, 307.	1.0	88
2	A Theoretical Review on Interfacial Thermal Transport at the Nanoscale. Small, 2018, 14, 1702769.	5.2	83
3	Mechanical, Thermodynamic and Electronic Properties of Wurtzite and Zinc-Blende GaN Crystals. Materials, 2017, 10, 1419.	1.3	52
4	First-principles investigation of adsorption behaviors of small molecules on penta-graphene. Nanoscale Research Letters, 2018, 13, 264.	3.1	51
5	First-Principles Investigation of the Adsorption Behaviors of CH2O on BN, AlN, GaN, InN, BP, and P Monolayers. Materials, 2019, 12, 676.	1.3	27
6	Gas sensing properties of two-dimensional penta-BP5: A first-principle study. Chemical Physics Letters, 2018, 706, 355-359.	1.2	16
7	First Principles Study of Gas Molecules Adsorption on Monolayered Î²-SnSe. Coatings, 2019, 9, 390.	1.2	11
8	Influence of microstructure inhomogeneity on the current density and temperature gradient in microscale line-type Sn58Bi solder joints under current stressing. Microelectronics Reliability, 2020, 115, 113995.	0.9	11
9	First-Principles Study on the Elastic Mechanical Properties and Anisotropies of Goldâ€“Copper Intermetallic Compounds. Metals, 2022, 12, 959.	1.0	9
10	Influence of Phase Inhomogeneity on Electromigration Behavior in Cu/Sn-58Bi/Cu Solder Joint. Journal of Electronic Materials, 2019, 48, 3410-3414.	1.0	6
11	Stress Concentration Induced by the Crystal Orientation in the Transient-Liquid-Phase Bonded Joint of Single-Crystalline Ni3Al. Materials, 2019, 12, 2765.	1.3	5
12	Crystallographic Characteristic Effect of Cu Substrate on Serrated Cathode Dissolution in Cu/Snâ€“3.0Agâ€“0.5Cu/Cu Solder Joints during Electromigration. Materials, 2021, 14, 2486.	1.3	5
13	Size effect on tensile performance of microscale Cu/Sn3.0Ag0.5Cu/Cu joints at low temperatures. Journal of Materials Science: Materials in Electronics, 2021, 32, 28454-28467.	1.1	5
14	Weakened strengthening effect in the Ag added microscale SnBi joints under current stressing. Materials Letters, 2022, 312, 131677.	1.3	4
15	The Mechanical Properties and Elastic Anisotropy of Î·â€²-Cu6Sn5 and Cu3Sn Intermetallic Compounds. Crystals, 2021, 11, 1562.	1.0	4
16	Shear performance of microscale ball grid array structure Cu(Ni)/Snâ€“3.0Agâ€“0.5Cu/Cu(Ni) solder joints at low temperatures. Materials Today Communications, 2022, 30, 103149.	0.9	3
17	Influence of Pressure on the Mechanical and Electronic Properties of Wurtzite and Zinc-Blende GaN Crystals. Crystals, 2018, 8, 428.	1.0	2
18	Asymmetric Long-Range Surface Plasmon Polariton Waveguides for Sensing Applications. IEEE Photonics Journal, 2019, 11, 1-9.	1.0	1

#	Article	IF	Citations
19	Influence of Microstructure Evolution on the Current Density and Temperature Gradient of Line-Type Cu/Sn58Bi/Cu Microscale Solder Joints Under Current Stressing. Journal of Electronic Materials, 2022, 51, 1116-1127.	1.0	1
20	Influence of microstructure inhomogeneity on the electromigration behavior of flip chip solder joints. , 2016, , .		0
21	Adsorption behavior of HCOOH on the crystal surfaces of Cu(111) and (100). , 2021, , .		0
22	Influence of phase inhomogeneity on the mechanical behavior of microscale Cu/Snâ€"58Bi/Cu solder joints. Journal of Materials Science: Materials in Electronics, 2022, 33, 244.	1.1	0